

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
24 March 2005 (24.03.2005)

PCT

(10) International Publication Number
WO 2005/027274 A1

(51) International Patent Classification⁷: **H01R 12/22**

(21) International Application Number:
PCT/US2004/024412

(22) International Filing Date: 29 July 2004 (29.07.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
10/658,019 9 September 2003 (09.09.2003) US

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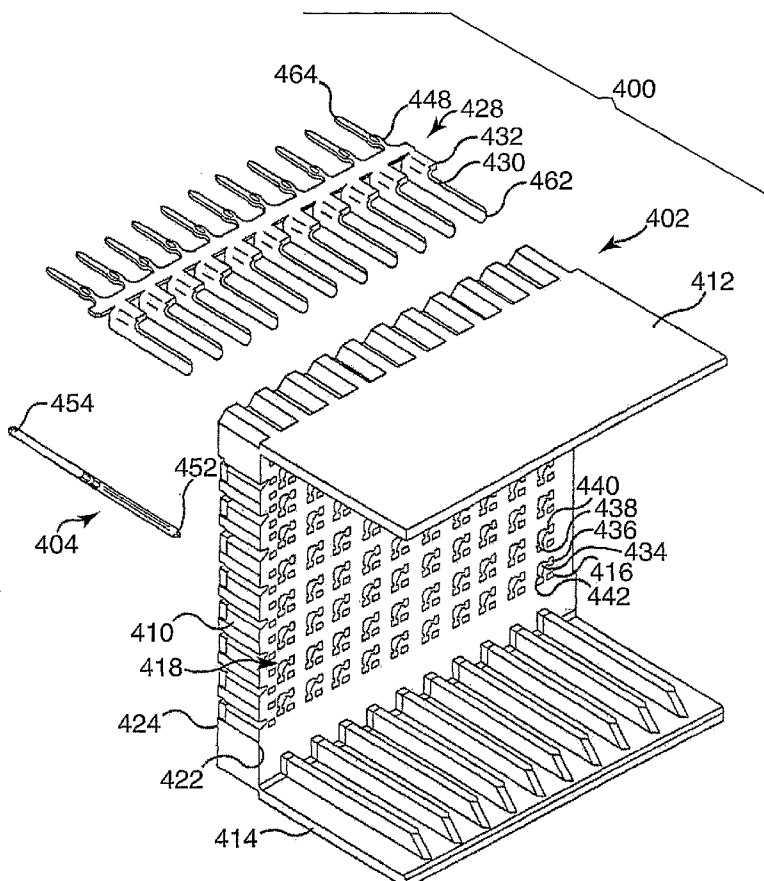
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(81) Designated States (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,

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(54) Title: INTERCONNECT SYSTEM



(57) Abstract: Disclosed herein are backplane interconnect systems that use surface mount technology for mating conductive pins (404) in a header connector (400) to surface mount pads (36) on a printed circuit board (34). In particular, the interconnect system uses a plurality of conductive pins (404) that are not fully inserted into the body of the header connector, thus allowing them to move during mating with a printed circuit board. In this way, the interconnect system exhibits self-leveling characteristics.

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FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI,
SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ,
GW, ML, MR, NE, SN, TD, TG).

Published:

— *with international search report*

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